

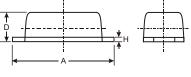
# 1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER PowerDI<sup>™</sup>123

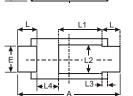
## **Features**

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- High Surge Capability
- High Current Capability and Low Forward Voltage Drop

# **Mechanical Data**

- Case: PowerDI™123, Plastic
- Plastic Material: UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Polarity: Cathode Band
- Terminals: Matte Tin Finish (Lead Free), Solderable per MIL-STD-202, Method 208
- Marking: Date Code & Type Code, See Page 3
- Type Code: F04
- Weight: 0.01 grams (approx.)
- Ordering Information: See Page 3





	PowerDI <sup>™</sup> 123										
Dim	Min	Max	Тур								
Α	3.50	3.90	3.70								
В	2.60	3.00	2.80								
С	1.63	1.93	1.78								
D	0.93	1.00	0.98								
E	0.85	1.25	1.00								
Н	0.15	0.25	0.20								
L	0.45	0.85	0.65								
L1		_	1.35								
L2			1.10								
L3			0.20								
L4	0.90	1.30	1.05								
All Dimensions in mm											

### **Maximum Ratings** @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

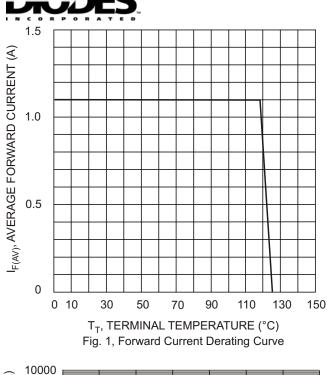
Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Average Forward Current @ T <sub>T</sub> = 119°C	I <sub>F(AV)</sub>	1.1	Α
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	40	А
Power Dissipation (Note 1)	P <sub>D</sub>	1.67	W
Power Dissipation (Note 2)	P <sub>D</sub>	556	mW
Thermal Resistance Junction to Ambient (Note 1)	R <sub>θ</sub> JA	60	°C/W
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	180	°C/W
Thermal Resistance Junction to Soldering (Note 3)	R <sub>θJS</sub>	10	°C/W
Operating Temperature Range	Tj	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

# **Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise specified

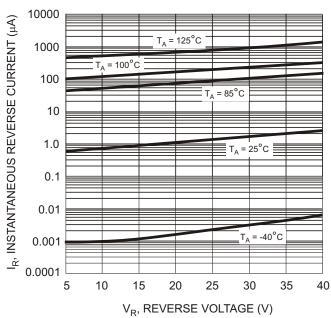
Characteristic		Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V <sub>(BR)R</sub>	40	_	_	V	$I_R = 20\mu A$
Forward Voltage (Note 4)	V <sub>F</sub>	_	0.45 0.53	0.51	V	I <sub>F</sub> = 0.5A I <sub>F</sub> = 1.1A
Leakage Current (Note 4)	I <sub>R</sub>	_	_	20 6.0	μA mA	V <sub>R</sub> = 40V, T <sub>A</sub> = 25°C V <sub>R</sub> = 40V, T <sub>A</sub> = 100°C
Total Capacitance	Ст	_	28	_	pF	V <sub>R</sub> = 10V, f = 1.0MHz

Notes:

- 1. Part mounted on 2"x2" GETEK board with 1"x1" copper pad, 25% anode, 75% cathode.
- 2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. Theoretical R<sub>0JS</sub> calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
- 4. Short duration pulse test to minimize self-heating effect.



0.01 0.0



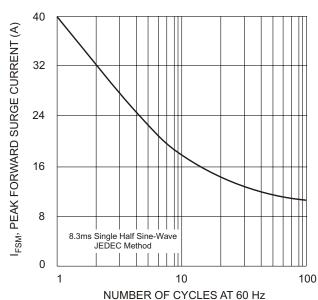


Fig. 3, Typical Pulsed Reverse Characteristics

Fig. 4, Maximum Non-Repetitive Peak Forward Surge Current



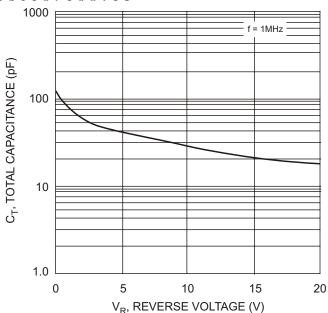


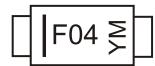
Fig. 5, Typical Total Capacitance vs Reverse Voltage

# Ordering Information (Note 5)

Device	Packaging	Shipping		
DFLS140-7	PowerDI <sup>™</sup> 123	3000/Tape & Reel		

Notes: 5. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



F04 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: P = 2003) M = Month (ex: 9 = September)

## Date Code Key

Year	2003	2004	2005	2006	2007	2008	2009	
Code	Р	R	S	Т	U	V	W	

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D